



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TO-220 (HVM)					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	80	20 000	200 °C + N2	0	0.00
HAST	1700	202 000	130 °C, 85 % RH	0	0.00
Power Cycle	240	1 440 000	DELTA T _j = 100 °C	0	0.00
Pressure Pot	1320	126 720	121°, 15 PSIG	0	0.00
Solder DUNK	85	255	260 °C, 10 s	0	0.00
Temp. Cycle	1480	1 358 500	-55 °C to 150 °C	0	0.00